

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1421cg-2.5#trpbf

(Engineering Calculation)

SSOP

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TOTAL MASS (g) : 0.162873

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004420 | 1000000 | 27137.7773438 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.075163 | 975000 | 461483.375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001850 | 24000 | 11358.5712891 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000023 | 300 | 141.214660645 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000054 | 700 | 331.547485352 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.077090 | 1000000 | 473314.75 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.003400 | 1000000 | 20872.7558594 | | |
| | | External Plating Total: | | | | 0.003400 | 1000000 | 20872.7558594 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000617 | 1000000 | 3788.23706055 | | |
| Internal Plating Total: | | | | 0.000617 | 1000000 | 3788.23706055 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001185 | 750000 | 7275.625 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000395 | 250000 | 2425.20849609 | | |
| Die Attach Total: | | | | 0.001580 | 1000000 | 9700.83398438 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.007726 | 103000 | 47435.8515625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.067134 | 895000 | 412187.1875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000150 | 2000 | 920.965270996 | | |
| | | Encapsulation Total: | | | | 0.075010 | 1000000 | 460544.03125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000756 | 1000000 | 4641.66455078 | | |
| | | | | | TOTAL MASS (g) : | 0.162873 | | |